Welcome to E-XFL.COM

Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Active
Core Processor	PowerPC G2_LE
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	266MHz
Co-Processors/DSP	Communications; RISC CPM
RAM Controllers	DRAM, SDRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10/100Mbps (3)
SATA	-
USB	USB 2.0 (1)
Voltage - I/O	3.3V
Operating Temperature	0°C ~ 105°C (TA)
Security Features	-
Package / Case	516-BBGA
Supplier Device Package	516-PBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mpc8275vrmiba

  - Includes all of the configuration registers (which are automatically loaded from the EPROM and used to configure the MPC8280) required by the PCI standard as well as message and doorbell registers
  - Supports the I_2O standard
  - Hot-swap friendly (supports the hot swap specification as defined by PICMG 2.1 R1.0 August 3, 1998)
  - Support for 66.67/83.33/100 MHz, 3.3 V specification
  - 60x-PCI bus core logic that uses a buffer pool to allocate buffers for each port
  - Uses the local bus signals, removing need for additional pins
- System interface unit (SIU)
  - Clock synthesizer
  - Reset controller
  - Real-time clock (RTC) register
  - Periodic interrupt timer
  - Hardware bus monitor and software watchdog timer
  - IEEE 1149.1 JTAG test access port
- 12-bank memory controller
  - Glueless interface to SRAM, page mode SDRAM, DRAM, EPROM, Flash, and other user-definable peripherals
  - Byte write enables and selectable parity generation
  - 32-bit address decodes with programmable bank size
  - Three user-programmable machines, general-purpose chip-select machine, and page mode pipeline SDRAM machine
  - Byte selects for 64-bit bus width (60x) and byte selects for 32-bus width (local)
  - Dedicated interface logic for SDRAM
- CPU core can be disabled and the device can be used in slave mode to an external core
- Communications processor module (CPM)
  - Embedded 32-bit communications processor (CP) uses a RISC architecture for flexible support for communications protocols
  - Interfaces to G2_LE core through an on-chip 32 KB dual-port data RAM, an on-chip 32 KB dual-port instruction RAM and DMA controller
  - Serial DMA channels for receive and transmit on all serial channels
  - Parallel I/O registers with open-drain and interrupt capability
  - Virtual DMA functionality executing memory-to-memory and memory-to-I/O transfers
  - Three fast communications controllers supporting the following protocols:
    - 10/100-Mbit Ethernet/IEEE 802.3 CDMA/CS interface through media independent interface (MII) or reduced media independent interface (RMII)

2 **Caution:** VDD/VCCSYN must not exceed VDDH by more than 0.4 V during normal operation. It is recommended that VDD/VCCSYN should be raised before or simultaneous with VDDH during power-on reset. VDD/VCCSYN may exceed VDDH by more than 0.4 V during power-on reset for no more than 100 ms.

3 **Caution:** VDDH can exceed VDD/VCCSYN by 3.3 V during power on reset by no more than 100 mSec. VDDH should not exceed VDD/VCCSYN by more than 2.5 V during normal operation.

4 **Caution:** VIN must not exceed VDDH by more than 2.5 V at any time, including during power-on reset.

This table lists recommended operational voltage conditions.

Table 4. Recommended Operating Conditions[1]

Rating	Symbol	Value	Unit
Core supply voltage	VDD	1.45 – 1.60	V
PLL supply voltage	VCCSYN	1.45 – 1.60	V
I/O supply voltage	VDDH	3.135 – 3.465	V
Input voltage	VIN	GND (–0.3) – 3.465	V
Junction temperature (maximum)	T_j	105[2]	°C
Ambient temperature	T_A	0–70[2]	°C

1 **Caution:** These are the recommended and tested operating conditions. Proper operation outside of these conditions is not guaranteed.

2 Note that for extended temperature parts the range is $(-40)_{T_A} – 105_{T_j}$.

This SoC contains circuitry protecting against damage due to high static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (either GND or V_{CC}).

This figure shows the undershoot and overshoot voltage of the 60x and local bus memory interface of the SoC. Note that in PCI mode the I/O interface is different.

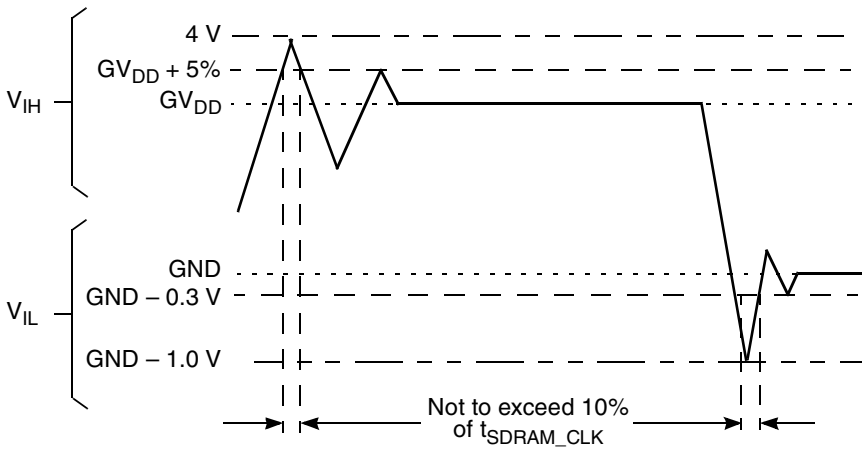


Figure 2. Overshoot/Undershoot Voltage

3 DC Electrical Characteristics

This table shows DC electrical characteristics.

Table 5. DC Electrical Characteristics[1]

Characteristic	Symbol	Min	Max	Unit
Input high voltage—all inputs except TCK, $\overline{\text{TRST}}$ and $\overline{\text{PORESET}}$[2]	V_{IH}	2.0	3.465	V
Input low voltage	V_{IL}	GND	0.8	V
CLKIN input high voltage	V_{IHC}	2.4	3.465	V
CLKIN input low voltage	V_{ILC}	GND	0.4	V
Input leakage current, V_{IN} = VDDH[3]	I_{IN}	—	10	μA
Hi-Z (off state) leakage current, V_{IN} = VDDH[3]	I_{OZ}	—	10	μA
Signal low input current, V_{IL} = 0.8 V[4]	I_L	—	1	μA
Signal high input current, V_{IH} = 2.0 V	I_H	—	1	μA
Output high voltage, I_{OH} = –2 mA except UTOPIA mode, and open drain pins In UTOPIA mode[5] (UTOPIA pins only): I_{OH} = -8.0mA PA[0-31] PB[4-31] PC[0-31] PD[4-31]	V_{OH}	2.4	—	V
In UTOPIA mode[5] (UTOPIA pins only): I_{OL} = 8.0mA PA[0-31] PB[4-31] PC[0-31] PD[4-31]	V_{OL}	—	0.5	V

5 Power Dissipation

This table provides preliminary, estimated power dissipation for various configurations. Note that suitable thermal management is required to ensure the junction temperature does not exceed the maximum specified value. Also note that the I/O power should be included when determining whether to use a heat sink. For a complete list of possible clock configurations, see Section 7, “Clock Configuration Modes.”

Table 7. Estimated Power Dissipation for Various Configurations[1]

Bus (MHz)	CPM Multiplication Factor	CPM (MHz)	CPU Multiplication Factor	CPU (MHz)	P_{INT}(W)[2,3]	
					Vddl 1.5 Volts	
					Nominal	Maximum
66.67	2.5	166	3.5	233	0.95	1.0
66.67	2.5	166	4	266	1.0	1.05
66.67	3	200	4	266	1.05	1.1
66.67	3.5	233	4.5	300	1.05	1.15
83.33	3	250	4	333	1.25	1.35
83.33	3	250	4.5	375	1.3	1.4
83.33	3.5	292	5	417	1.45	1.55
100	3	300	4	400	1.5	1.6
100	3	300	4.5	450	1.55	1.65

1 Test temperature = 105° C

2 $P_{INT} = I_{DD} \times V_{DD}$ Watts

3 Values do not include I/O. Add the following estimates for active I/O based on the following bus speeds:
66.7 MHz = 0.45 W (nominal), 0.5 W (maximum)
83.3 MHz = 0.5W (nominal), 0.6 W (maximum)
100 MHz = 0.6 W (nominal), 0.7 W (maximum)

NOTE

Activating data pipelining (setting BR*x*[DR] in the memory controller) improves the AC timing.

This table lists SIU input characteristics.

Table 13. AC Characteristics for SIU Inputs[1]

Spec Number		Characteristic	Value (ns)					
Setup	Hold		Setup			Hold		
			66 MHz	83 MHz	100 MHz	66 MHz	83 MHz	100 MHz
sp11	sp10	$\overline{\text{AACK}}$/$\overline{\text{TA}}$/$\overline{\text{TS}}$/$\overline{\text{DBG}}$/$\overline{\text{BG}}$/$\overline{\text{BR}}$/$\overline{\text{ARTRY}}$/ $\overline{\text{TEA}}$	6	5	3.5	0.5	0.5	0.5
sp12	sp10	Data bus in normal mode	5	4	3.5	0.5	0.5	0.5
sp13	sp10	Data bus in ECC and PARITY modes	7	5	3.5	0.5	0.5	0.5
sp13a	sp10	Pipeline mode—Data bus (with or without ECC/PARITY)	5	4	2.5	0.5	0.5	0.5
sp14	sp10	DP pins	7	5	3.5	0.5	0.5	0.5
sp14a	sp10	Pipeline mode—DP pins	—	4	2.5	—	0.5	0.5
sp15	sp10	All other pins	5	4	3.5	0.5	0.5	0.5

1 Input specifications are measured from the 50% level of the signal to the 50% level of the rising edge of CLKIN. Timings are measured at the pin.

This table lists SIU output characteristics.

Table 14. AC Characteristics for SIU Outputs[1]

Spec Number		Characteristic	Value (ns)					
Max	Min		Maximum Delay			Minimum Delay		
			66 MHz	83 MHz	100 MHz	66 MHz	83 MHz	100 MHz
sp31	sp30	$\overline{\text{PSDVAL}}$/$\overline{\text{TEA}}$/$\overline{\text{TA}}$	7	6	5.5	1	1	1
sp32	sp30	ADD/ADD_atr./BADDR/CI/GBL/WT	8	6.5	5.5	1	1	1
sp33a	sp30	Data bus[2]	6.5	6.5	5.5	0.7	0.7	0.7
sp33b	sp30	DP	6	5.5	5.5	1	1	1
sp34	sp30	Memory controller signals/ALE	6	5.5	5.5	1	1	1
sp35	sp30	All other signals	6	5.5	5.5	1	1	1
sp35a	sp30	AP	7	7	7	1	1	1

1 Output specifications are measured from the 50% level of the rising edge of CLKIN to the 50% level of the signal. Timings are measured at the pin.

2 To achieve 1 ns of hold time at 66, 83, or 100 MHz, a minimum loading of 20 pF is required.

1 The “low” values are the minimum allowable frequencies for a given clock mode. The minimum bus frequency in a table entry guarantees only the required minimum CPU operating frequency. The “high” values are for the purpose of illustration only. Users must select a mode and input bus frequency so that the resulting configuration does not violate the frequency rating of the user’s device. The minimum CPM frequency is 120 MHz. Minimum CPU frequency is determined by the clock mode. For modes with a CPU multiplication factor <= 3, the minimum CPU frequency is 150 MHz for commercial temperature devices and 175 MHz for extended temperature devices. For modes with a CPU multiplication factor >= 3.5: for Rev0.1 the minimum CPU frequency is 250 MHz; for Rev A or later the minimum CPU frequency is 150 MHz for commercial temperature devices and 175 MHz for extended temperature devices.

2 As Table 17 shows, PCI_MODCK determines the PCI clock frequency range. See Table 20 for lower configurations.

3 MODCK_H = hard reset configuration word [28–31]. MODCK[1-3] = three hardware configuration pins.

4 60x and local bus frequency. Identical to CLKIN.

5 CPM multiplication factor = CPM clock/bus clock

6 CPU multiplication factor = Core PLL multiplication factor

Table 20. Clock Configurations for PCI Host Mode (PCI_MODCK=1)[1,2]

Mode[3]	Bus Clock[4] (MHz)		CPM Multiplication Factor[5]	CPM Clock (MHz)		CPU Multiplication Factor[6]	CPU Clock (MHz)		PCI Division Factor	PCI Clock (MHz)	
MODCK_H-MODCK[1-3]	Low	High		Low	High		Low	High		Low	High
Default Modes (MODCK_H=0000)											
0000_000	60.0	100.0	2	120.0	200.0	2.5	150.0	250.0	4	30.0	50.0
0000_001	50.0	100.0	2	100.0	200.0	3	150.0	300.0	4	25.0	50.0
0000_010	60.0	120.0	2.5	150.0	300.0	3	180.0	360.0	6	25.0	50.0
0000_011	60.0	120.0	2.5	150.0	300.0	3.5	210.0	420.0	6	25.0	50.0
0000_100	60.0	120.0	2.5	150.0	300.0	4	240.0	480.0	6	25.0	50.0
0000_101	50.0	100.0	3	150.0	300.0	3	150.0	300.0	6	25.0	50.0
0000_110	50.0	100.0	3	150.0	300.0	3.5	175.0	350.0	6	25.0	50.0
0000_111	50.0	100.0	3	150.0	300.0	4	200.0	400.0	6	25.0	50.0
Full Configuration Modes											
0001_000	50.0	100.0	3	150.0	300.0	5	250.0	500.0	6	25.0	50.0
0001_001	50.0	100.0	3	150.0	300.0	6	300.0	600.0	6	25.0	50.0
0001_010	50.0	100.0	3	150.0	300.0	7	350.0	700.0	6	25.0	50.0
0001_011	50.0	100.0	3	150.0	300.0	8	400.0	800.0	6	25.0	50.0
0010_000	50.0	100.0	4	200.0	400.0	5	250.0	500.0	8	25.0	50.0
0010_001	50.0	100.0	4	200.0	400.0	6	300.0	600.0	8	25.0	50.0
0010_010	50.0	100.0	4	200.0	400.0	7	350.0	700.0	8	25.0	50.0
0010_011	50.0	100.0	4	200.0	400.0	8	400.0	800.0	8	25.0	50.0
0010_100	37.5	75.0	4	150.0	300.0	5	187.5	375.0	6	25.0	50.0
0010_101	37.5	75.0	4	150.0	300.0	5.5	206.3	412.5	6	25.0	50.0

Table 23. MPC8280 and MPC8270 (ZU and VV Packages) Pinout List (continued)

Pin Name		Ball
MPC8280/MPC8270	MPC8280 only	
D51		C12
D52		B10
D53		A7
D54		C6
D55		D5
D56		B18
D57		B16
D58		E14
D59		D12
D60		C10
D61		E8
D62		D6
D63		C2
DP0/$\overline{\text{RSRV}}$/$\overline{\text{EXT\_BR2}}$		B22
$\overline{\text{IRQ1}}$/DP1/$\overline{\text{EXT\_BG2}}$		A22
$\overline{\text{IRQ2}}$/DP2/$\overline{\text{TLBISYNC}}$/$\overline{\text{EXT\_DBG2}}$		E21
$\overline{\text{IRQ3}}$/DP3/$\overline{\text{CKSTP\_OUT}}$/$\overline{\text{EXT\_BR3}}$		D21
$\overline{\text{IRQ4}}$/DP4/$\overline{\text{CORE\_SRESET}}$/$\overline{\text{EXT\_BG3}}$		C21
$\overline{\text{IRQ5}}$/$\overline{\text{CINT}}$/DP5/$\overline{\text{TBEN}}$/$\overline{\text{EXT\_DBG3}}$		B21
$\overline{\text{IRQ6}}$/DP6/CSE0		A21
$\overline{\text{IRQ7}}$/DP7/CSE1		E20
$\overline{\text{PSDVAL}}$		V3
$\overline{\text{TA}}$		C22
$\overline{\text{TEA}}$		V5
$\overline{\text{GBL}}$/$\overline{\text{IRQ1}}$		W1
$\overline{\text{CI}}$/BADDR29/$\overline{\text{IRQ2}}$		U2
$\overline{\text{WT}}$/BADDR30/$\overline{\text{IRQ3}}$		U3
$\overline{\text{L2\_HIT}}$/$\overline{\text{IRQ4}}$		Y4
$\overline{\text{CPU\_BG}}$/BADDR31/$\overline{\text{IRQ5}}$/$\overline{\text{CINT}}$		U4
$\overline{\text{CPU\_DBG}}$		R2
$\overline{\text{CPU\_BR}}$		Y3
$\overline{\text{CS0}}$		F25
$\overline{\text{CS1}}$		C29

Table 23. MPC8280 and MPC8270 (ZU and VV Packages) Pinout List (continued)

Pin Name		Ball
MPC8280/MPC8270	MPC8280 only	
LSDWE/LGPL1/PCI_MODCKH1		C28
LOE/LSDRAS/LGPL2/PCI_MODCKH2		E26
LSDCAS/LGPL3/PCI_MODCKH3		D25
LGTA/LUPMWAIT/LGPL4/LPBS		C26
LGPL5/LSDAMUX/PCI_MODCK		B27
LWR		D28
L_A14/PAR		N27
L_A15/FRAME/SMI		T29
L_A16/TRDY		R27
L_A17/IRDY/CKSTP_OUT		R26
L_A18/STOP		R29
L_A19/DEVSEL		R28
L_A20/IDSEL		W29
L_A21/PERR		P28
L_A22/SERR		N26
L_A23/REQ0		AA27
L_A24/REQ1/HSEJSW		P29
L_A25/GNT0		AA26
L_A26/GNT1/HSLED		N25
L_A27/GNT2/HSENUM		AA25
L_A28/RST/CORE_SRESET		AB29
L_A29/INTA		AB28
L_A30/REQ2		P25
L_A31/DLLOUT		AB27
LCL_D0/AD0		H29
LCL_D1/AD1		J29
LCL_D2/AD2		J28
LCL_D3/AD3		J27
LCL_D4/AD4		J26
LCL_D5/AD5		J25
LCL_D6/AD6		K25
LCL_D7/AD7		L29
LCL_D8/AD8		L27

Table 23. MPC8280 and MPC8270 (ZU and VV Packages) Pinout List (continued)

Pin Name		Ball
MPC8280/MPC8270	MPC8280 only	
LCL_D9/AD9		L26
LCL_D10/AD10		L25
LCL_D11/AD11		M29
LCL_D12/AD12		M28
LCL_D13/AD13		M27
LCL_D14/AD14		M26
LCL_D15/AD15		N29
LCL_D16/AD16		T25
LCL_D17/AD17		U27
LCL_D18/AD18		U26
LCL_D19/AD19		U25
LCL_D20/AD20		V29
LCL_D21/AD21		V28
LCL_D22/AD22		V27
LCL_D23/AD23		V26
LCL_D24/AD24		W27
LCL_D25/AD25		W26
LCL_D26/AD26		W25
LCL_D27/AD27		Y29
LCL_D28/AD28		Y28
LCL_D29/AD29		Y25
LCL_D30/AD30		AA29
LCL_D31/AD31		AA28
LCL_DP0/C0/$\overline{\text{BE0}}$		L28
LCL_DP1/C1/$\overline{\text{BE1}}$		N28
LCL_DP2/C2/$\overline{\text{BE2}}$		T28
LCL_DP3/C3/$\overline{\text{BE3}}$		W28
$\overline{\text{IRQ0}}$/$\overline{\text{NMI\_OUT}}$		T1
$\overline{\text{IRQ7}}$/$\overline{\text{INT\_OUT}}$/$\overline{\text{APE}}$		D1
$\overline{\text{TRST}}$[1]		AH3
TCK		AG5
TMS		AJ3
TDI		AE6

Table 23. MPC8280 and MPC8270 (ZU and VV Packages) Pinout List (continued)

Pin Name		Ball
MPC8280/MPC8270	MPC8280 only	
PA17/FCC1_MII_HDLC_RXD0/ FCC1_MII_TRAN_RXD/ FCCI_RMII_RXD0	FCC1_UT8_RXD7/ FCC1_UT16_RXD15	AE16[2]
PA18/FCC1_MII_HDLC_TXD0/ FCC1_MII_TRAN_TXD/ FCC1_RMII_TXD0	FCC1_UT8_TXD7/FCC1_UT16_TXD15	AJ16[2]
PA19/FCC1_MII_HDLC_TXD1/ FCC1_RMII_TXD1	FCC1_UT8_TXD6/FCC1_UT16_TXD14	AG15[2]
PA20/FCC1_MII_HDLC_TXD2	FCC1_UT8_TXD5/FCC1_UT16_TXD13	AJ13[2]
PA21/FCC1_MII_HDLC_TXD3	FCC1_UT8_TXD4/FCC1_UT16_TXD12	AE13[2]
PA22	FCC1_UT8_TXD3/FCC1_UT16_TXD11	AF12[2]
PA23	FCC1_UT8_TXD2/FCC1_UT16_TXD10	AG11[2]
PA24/MSNUM1	FCC1_UT8_TXD1/FCC1_UT16_TXD9	AH9[2]
PA25/MSNUM0	FCC1_UT8_TXD0/FCC1_UT16_TXD8	AJ8[2]
PA26/FCC1_RMII_RX_ER	FCC1_UTM_RXCLAV/ FCC1_UTS_RXCLAV	AH7[2]
PA27/FCC1_MII_RX_DV/ FCC1_RMII_CRS_DV	FCC1_UT_RXSOC	AF7[2]
PA28/FCC1_MII_TX_EN/ FCC1_RMII_TX_EN	$\overline{\text{FCC1\_UTM\_RXENB}}$/ $\overline{\text{FCC1\_UTS\_RXENB}}$	AD5[2]
PA29/FCC1_MII_TX_ER	FCC1_UT_TXSOC	AF1[2]
PA30/FCC1_MII_CRS/$\overline{\text{FCC1\_RTS}}$	FCC1_UTM_TXCLAV/ FCC1_UTS_TXCLAV	AD3[2]
PA31/FCC1_MII_COL	$\overline{\text{FCC1\_UTM\_TXENB}}$/ $\overline{\text{FCC1\_UTS\_TXENB}}$	AB5[2]
PB4/FCC3_MII_HDLC_TXD3/ L1RSYNCA2/$\overline{\text{FCC3\_RTS}}$	FCC2_UT8_RXD0	AD28[2]
PB5/FCC3_MII_HDLC_TXD2/ L1TSYNCA2/L1GNTA2	FCC2_UT8_RXD1	AD26[2]
PB6/FCC3_MII_HDLC_TXD1/ FCC3_RMII_TXD1/ L1RXDA2/L1RXD0A2	FCC2_UT8_RXD2	AD25[2]
PB7/FCC3_MII_HDLC_TXD0/ FCC3_RMII_TXD0/ FCC3_TXD/L1TXDA2/L1TXD0A2	FCC2_UT8_RXD3	AE26[2]
PB8/FCC3_MII_HDLC_RXD0/ FCC3_RMII_RXD0/ FCC3_RXD/TXD3	FCC2_UT8_TXD3/L1RSYNCD1	AH27[2]
PB9/FCC3_MII_HDLC_RXD1/ FCC3_RMII_RXD1/L1TXD2A2	FCC2_UT8_TXD2/L1TSYNCD1/ L1GNTD1	AG24[2]

Table 23. MPC8280 and MPC8270 (ZU and VV Packages) Pinout List (continued)

Pin Name		Ball
MPC8280/MPC8270	MPC8280 only	
PB10/FCC3_MII_HDLC_RXD2	FCC2_UT8_TXD1/L1RXDD1	AH24[2]
PB11/FCC3_MII_HDLC_RXD3	FCC2_UT8_TXD0/L1TXDD1	AJ24[2]
PB12/FCC3_MII_CRS/TXD2	L1CLKOB1/L1RSYNCC1	AG22[2]
PB13/FCC3_MII_COL/L1TXD1A2	$\overline{\text{L1RQB1}}$/L1TSYNCC1/L1GNTC1	AH21[2]
PB14/FCC3_MII_RMII_TX_EN//RXD3	L1RXDC1	AG20[2]
PB15/FCC3_MII_TX_ER/RXD2	L1TXDC1	AF19[2]
PB16/FCC3_MII_RMII_RX_ER/CLK18	L1CLKOA1	AJ18[2]
PB17/FCC3_MII_RX_DV/CLK17/ FCC3_RMII_CRS_DV	L1RQA1	AJ17[2]
PB18/FCC2_MII_HDLC_RXD3/ L1CLKOD2/L1RXD2A2	FCC2_UT8_RXD4	AE14[2]
PB19FCC2_MII_HDLC_RXD2/ L1RQD2/L1RXD3A2	FCC2_UT8_RXD5	AF13[2]
PB20/FCC2_MII_HDLC_RMII_RXD1/ L1RSYNCD2	FCC2_UT8_RXD6/L1TXD1A1	AG12[2]
PB21//FCC2_MII_HDLC_RMII_RXD0/ FCC2_TRAN_RXD/L1TSYNCD2/ L1GNTD2	FCC2_UT8_RXD7/L1TXD2A1	AH11[2]
PB22/FCC2_MII_HDLC_TXD0/ FCC2_TXD/FCC2_RMII_TXD0/ L1RXDD2	FCC2_UT8_TXD7/L1RXD1A1	AH16[2]
PB23/FCC2_MII_HDLC_TXD1/ L1RXD2A1/L1TXDD2/ FCC2_RMII_TXD1	FCC2_UT8_TXD6/L1RXD2A1	AE15[2]
PB24/FCC2_MII_HDLC_TXD2/ L1RSYNCC2	FCC2_UT8_TXD5/L1RXD3A1	AJ9[2]
PB25/FCC2_MII_HDLC_TXD3/ L1TSYNCC2/L1GNTC2	FCC2_UT8_TXD4/L1TXD3A1	AE9[2]
PB26/FCC2_MII_CRS/L1RXDC2	FCC2_UT8_TXD1	AJ7[2]
PB27/FCC2_MII_COL/L1TXDC2	FCC2_UT8_TXD0	AH6[2]
PB28/FCC2_MII_RX_ER/ FCC2_RMII_RX_ER/$\overline{\text{FCC2\_RTS}}$/ L1TSYNCB2/L1GNTB2/TXD1		AE3[2]
PB29/L1RSYNCB2/FCC2_MII_TX_EN/ FCC2_RMII_TX_EN	FCC2_UTM_RXCLAV/ FCC2_UTS_RXCLAV	AE2[2]
PB30/FCC2_MII_RX_DV/ FCC2_RMII_CRS_DV/L1RXDB2	FCC2_UT_TXSOC	AC5[2]
PB31/FCC2_MII_TX_ER/L1TXDB2	FCC2_UT_RXSOC	AC4[2]

Table 23. MPC8280 and MPC8270 (ZU and VV Packages) Pinout List (continued)

Pin Name		Ball
MPC8280/MPC8270	MPC8280 only	
Core power		U28, U29, K28, K29, A9, A19, B19, M1, M2, Y1, Y2, AC1, AC2, AH19, AJ19, AH10, AJ10, AJ5
Ground		AA5, AB1[6], AB2[7], AF21, AF14, AF8, AE7, AF11, AE17, AE23, AC26, AB25, Y26, V25, T26, R25, P26, M25, K27, H25, G26, D7, D10, D14, D16, D20, D23, C9, E11, E13, E15, E19, E22, B3, G5, H4, K5, M3, P5, T4, Y5, AA2, AC3

1 Should be tied to VDDH via a 2K Ω external pull-up resistor.

2 The default configuration of the CPM pins (PA[0–31], PB[4–31], PC[0–31], PD[4–31]) is input. To prevent excessive DC current, it is recommended to either pull unused pins to GND or VDDH, or to configure them as outputs.

3 Must be pulled down or left floating.

4 If PCI is not desired, must be pulled up or left floating.

5 Sphere is not connected to die.

6 GNDSYN (AB1): This pin exists as a separate ground signal in MPC826x(A) devices; it does not exist as a separate ground signal on the SoC. New designs must connect AB1 to GND and follow the suggestions in Section 4.6, "Layout Practices." Old designs in which the MPC8280 is used as a drop-in replacement can leave the pin connected to GND with the noise filtering capacitors.

7 XFC (AB2) pin: This pin is used in MPC826x(A) devices; it is not used in MPC8280 because there is no need for external capacitor to operate the PLL. New designs should connect AB2 (XFC) pin to GND. Old designs in which the SoC is used as a drop-in replacement can leave the pin connected to the current capacitor.

This table describes symbols used in Table 23.

Table 24. Symbol Legend

Symbol	Meaning
$\overline{\text{OVERBAR}}$	Signals with overbars, such as $\overline{\text{TA}}$, are active low.
UTM	Indicates that a signal is part of the UTOPIA master interface.
UTS	Indicates that a signal is part of the UTOPIA slave interface.
UT8	Indicates that a signal is part of the 8-bit UTOPIA interface.
UT16	Indicates that a signal is part of the 16-bit UTOPIA interface.
MII	Indicates that a signal is part of the media independent interface.
RMII	Indicates that a signal is part of the reduced media independent interface.

8.2 VR and ZQ Packages—MPC8275 and MPC8270

The following figures and table represent the alternate 516 PBGA package. For information on the standard package for the MPC8280 and the MPC8270, see Section 8.1, "ZU and VV Packages—MPC8280 and MPC8270.

Table 25. MPC8275 and MPC8270 (VR and ZQ Packages) Pinout List (continued)

Pin Name		Ball
MPC8275/MPC8270	MPC8275 only	
A0		D5
A1		E8
A2		C4
A3		B4
A4		A4
A5		D7
A6		D8
A7		C6
A8		B5
A9		B6
A10		C7
A11		C8
A12		A6
A13		D9
A14		F11
A15		B7
A16		B8
A17		C9
A18		A7
A19		B9
A20		E11
A21		A8
A22		D11
A23		B10
A24		C11
A25		A9
A26		B11
A27		C12
A28		D12
A29		A10
A30		B12
A31		B13
TT0		E7

Table 25. MPC8275 and MPC8270 (VR and ZQ Packages) Pinout List (continued)

Pin Name		Ball
MPC8275/MPC8270	MPC8275 only	
TT1		B3
TT2		F8
TT3		A3
TT4		C3
$\overline{\text{TBST}}$		F5
TSIZ0		E3
TSIZ1		E2
TSIZ2		E1
TSIZ3		E4
$\overline{\text{AACK}}$		D3
$\overline{\text{ARTRY}}$		C2
$\overline{\text{DBG}}$		A14
$\overline{\text{DBB}}$/$\overline{\text{IRQ3}}$		C15
D0		W4
D1		Y1
D2		V1
D3		P4
D4		N3
D5		K5
D6		J4
D7		G1
D8		AB1
D9		U4
D10		U2
D11		N6
D12		N1
D13		L1
D14		J5
D15		G3
D16		AA2
D17		W1
D18		T3
D19		T1

Table 25. MPC8275 and MPC8270 (VR and ZQ Packages) Pinout List (continued)

Pin Name		Ball
MPC8275/MPC8270	MPC8275 only	
D53		J2
D54		H5
D55		F3
D56		V3
D57		R5
D58		R2
D59		N5
D60		L2
D61		J3
D62		H1
D63		F4
DP0/$\overline{\text{RSRV}}$/$\overline{\text{EXT\_BR2}}$		AB3
$\overline{\text{IRQ1}}$/DP1/$\overline{\text{EXT\_BG2}}$		W5
$\overline{\text{IRQ2}}$/DP2/$\overline{\text{TLBISYNC}}$/$\overline{\text{EXT\_DBG2}}$		AC2
$\overline{\text{IRQ3}}$/DP3/$\overline{\text{CKSTP\_OUT}}$/$\overline{\text{EXT\_BR3}}$		AA3
$\overline{\text{IRQ4}}$/DP4/$\overline{\text{CORE\_SRESET}}$/$\overline{\text{EXT\_BG3}}$		AD1
$\overline{\text{IRQ5}}$/$\overline{\text{CINT}}$/DP5/$\overline{\text{TBEN}}$/$\overline{\text{EXT\_DBG3}}$		AC1
$\overline{\text{IRQ6}}$/DP6/CSE0		AB2
$\overline{\text{IRQ7}}$/DP7/CSE1		Y3
$\overline{\text{PSDVAL}}$		D15
$\overline{\text{TA}}$		Y4
$\overline{\text{TEA}}$		D16
$\overline{\text{GBL}}$/$\overline{\text{IRQ1}}$		E15
$\overline{\text{CI}}$/BADDR29/$\overline{\text{IRQ2}}$		D14
$\overline{\text{WT}}$/BADDR30/$\overline{\text{IRQ3}}$		E14
$\overline{\text{L2\_HIT}}$/$\overline{\text{IRQ4}}$		A17
$\overline{\text{CPU\_BG}}$/BADDR31/$\overline{\text{IRQ5}}$/$\overline{\text{CINT}}$		B14
$\overline{\text{CPU\_DBG}}$		F13
$\overline{\text{CPU\_BR}}$		B17
$\overline{\text{CS0}}$		AC6
$\overline{\text{CS1}}$		AD6
$\overline{\text{CS2}}$		AE6
$\overline{\text{CS3}}$		AB7

Table 25. MPC8275 and MPC8270 (VR and ZQ Packages) Pinout List (continued)

Pin Name		Ball
MPC8275/MPC8270	MPC8275 only	
CS4		AF7
CS5		AC7
CS6		AD7
CS7		AF8
CS8		AE8
CS9		AD8
CS10/BCTL1		AC8
CS11/AP0		AB8
BADDR27		C13
BADDR28		A12
ALE		D13
BCTL0		AF4
PWE0/PSDDQM0/PBS0		AA5
PWE1/PSDDQM1/PBS1		AE4
PWE2/PSDDQM2/PBS2		AD4
PWE3/PSDDQM3/PBS3		AF3
PWE4/PSDDQM4/PBS4		AB4
PWE5/PSDDQM5/PBS5		AE3
PWE6/PSDDQM6/PBS6		AF2
PWE7/PSDDQM7/PBS7		AD3
PSDA10/PGPL0		AE2
PSDWE/PGPL1		AD2
POE/PSDRAS/PGPL2		AE1
PSDCAS/PGPL3		AC3
PGTA/PUPMWAIT/PGPL4/PPBS		W6
PSDAMUX/PGPL5		AA4
LWE0/LSDDQM0/LBS0/PCI_CFG0		AC9
LWE1/LSDDQM1/LBS1/PCI_CFG1		AD9
LWE2/LSDDQM2/LBS2/PCI_CFG2		AE9
LWE3/LSDDQM3/LBS3/PCI_CFG3		AF9
LSDA10/LGPL0/PCI_MODCKH0		AB6
LSDWE/LGPL1/PCI_MODCKH1		AF5
LOE/LSDRAS/LGPL2/PCI_MODCKH2		AE5

Table 25. MPC8275 and MPC8270 (VR and ZQ Packages) Pinout List (continued)

Pin Name		Ball
MPC8275/MPC8270	MPC8275 only	
LSDCAS/LGPL3/PCI_MODCKH3		AD5
LGTA/LUPMWAIT/LGPL4/LPBS		AC5
LGPL5/LSDAMUX/PCI_MODCK		AB5
LWR		AF6
L_A14/PAR		AE13
L_A15/FRAME/SMI		AD15
L_A16/TRDY		AF16
L_A17/IRDY/CKSTP_OUT		AF15
L_A18/STOP		AE15
L_A19/DEVSEL		AE14
L_A20/IDSEL		AC17
L_A21/PERR		AD14
L_A22/SERR		AF13
L_A23/REQ0		AE20
L_A24/REQ1/HSEJSW		AC14
L_A25/GNT0		AC19
L_A26/GNT1/HSLED		AD13
L_A27/GNT2/HSENUM		AF21
L_A28/RST/CORE_SRESET		AF22
L_A29/INTA		AE21
L_A30/REQ2		AB14
L_A31/DLLOUT		AD20
LCL_D0/AD0		AB9
LCL_D1/AD1		AB10
LCL_D2/AD2		AC10
LCL_D3/AD3		AD10
LCL_D4/AD4		AE10
LCL_D5/AD5		AF10
LCL_D6/AD6		AF11
LCL_D7/AD7		AB12
LCL_D8/AD8		AB11
LCL_D9/AD9		AF12
LCL_D10/AD10		AE11

3 Must be pulled down or left floating.
4 If PCI is not desired, must be pulled up or left floating.
5 Sphere is not connected to die.
6 GNDSYN (B18): This pin exists as a separate ground signal in MPC826x(A) devices; it does not exist as a separate ground signal on the MPC8275/MPC8270. New designs must connect B18 to GND and follow the suggestions in Section 4.6, "Layout Practices." Old designs in which the MPC8275/MPC8270 is used as a drop-in replacement can leave the pin connected to GND with the noise filtering capacitors.
7 XFC (A18) pin: This pin is used in MPC826x(A) devices; it is not used in MPC8275/MPC8270 because there is no need for external capacitor to operate the PLL. New designs should connect A18 (XFC) pin to GND. Old designs in which the MPC8275/MPC8270 is used as a drop-in replacement can leave the pin connected to the current capacitor.

9 Package Description

This figure shows the side profile of the TBGA package to indicate the direction of the top surface view.

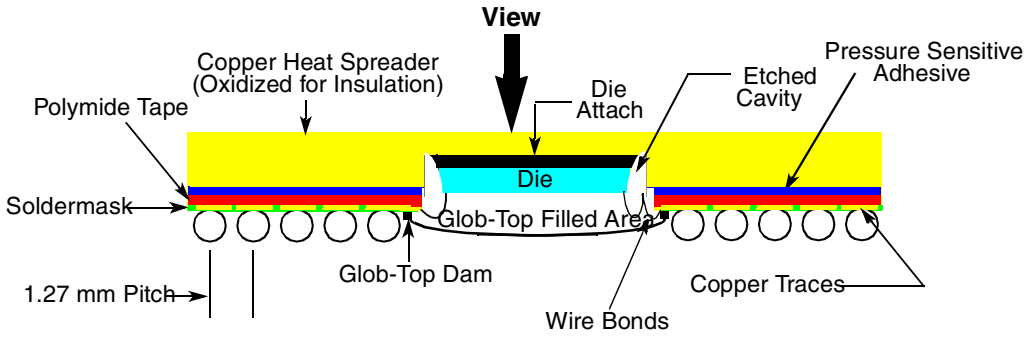


Figure 15. Side View of the TBGA Package

This figure shows the side profile of the PBGA package to indicate the direction of the top surface view.

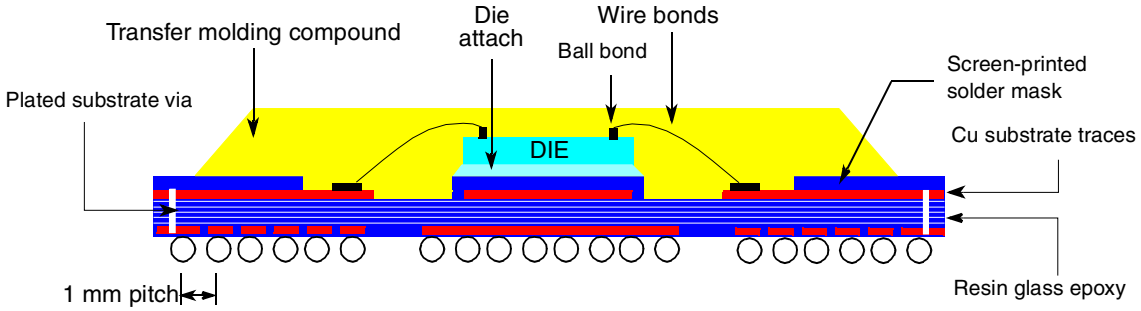
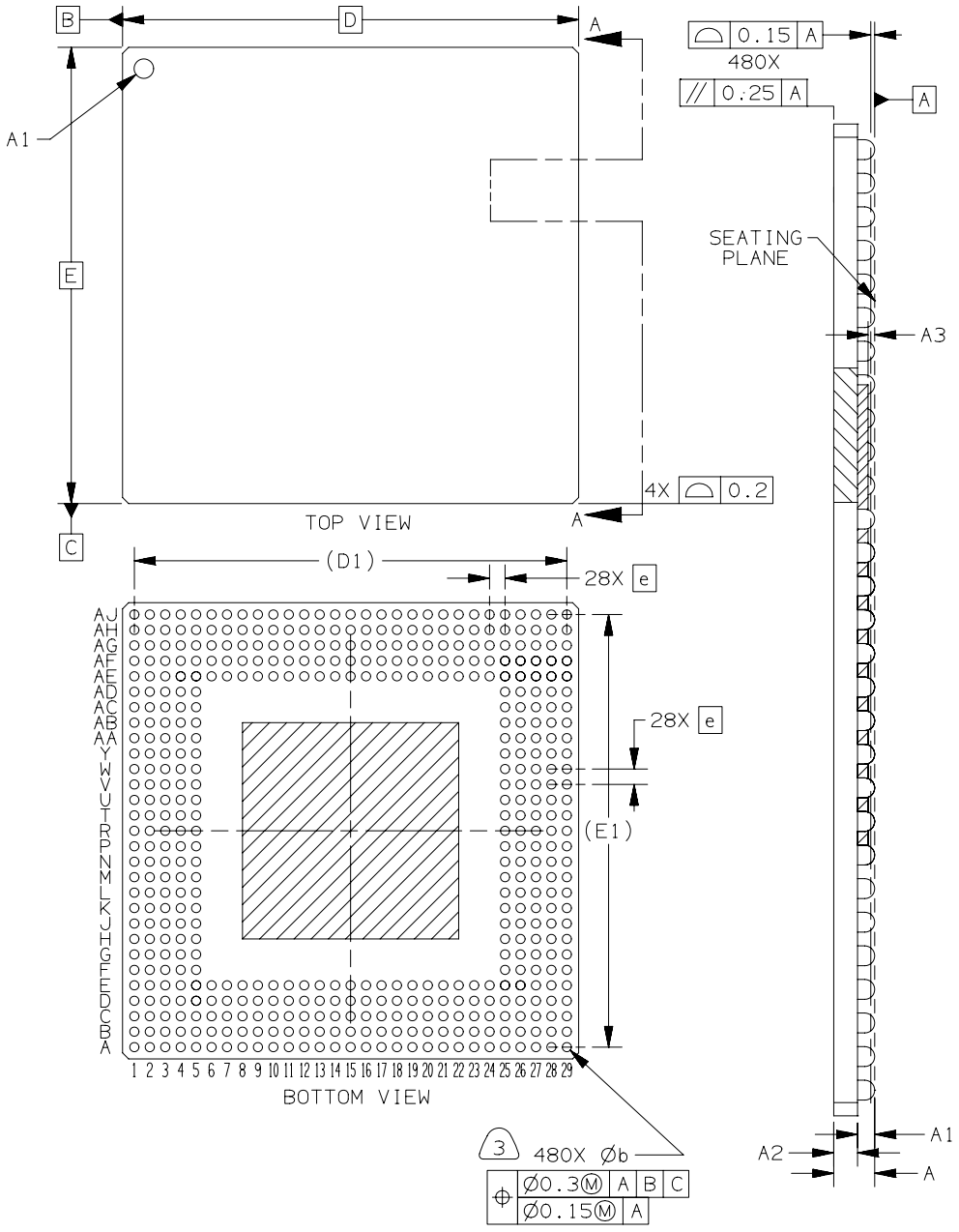


Figure 16. Side View of the PBGA Package Remove

9.2 Mechanical Dimensions

This figure provides the mechanical dimensions and bottom surface nomenclature of the 480 TBGA (ZU/VV) package. See Table 2, “HiP7 PowerQUICC II Device Packages.”



Dim	Millimeters	
	Min	Max
A	1.45	1.65
A1	0.60	0.70
A2	0.85	0.95
A3	0.25	—
b	0.65	0.85
D	37.50 BSC	
D1	35.56 REF	
e	1.27 BSC	
E	37.50 BSC	
E1	35.56 REF	

Notes:

1. Dimensions and Tolerancing per ASME Y14.5M-1994.
2. Dimensions in millimeters.
3. Dimension b is measured at the maximum solder ball diameter, parallel to primary data A.
4. Primary data A and the seating plane are defined by the spherical crowns of the solder balls.

Figure 17. Mechanical Dimensions and Bottom Surface Nomenclature—480 TBGA

Table 27. Document Revision History (continued)

Revision	Date	Substantive Changes
0.3	6/2003	• Removal of notes stating “no local bus” on VR-package devices. The MPC8270VR and the MPC8275VR have local bus support. • References to “G2 core” changed to “G2_LE core.” See the *G2 Core Reference Manual* (G2CORERM/D). • Addition of VCCSYN to “Note” below Table 4, and to note 3 of Table 5 • Figure 2: New • Table 5: Addition of note 1 • Table 10: Addition of θ_{JB} and θ_{JC}. Modifications to ZU package values. • Table 12: Addition of various configurations, Modification of values. Addition of note 3. • Table 9: Addition of 66 MHZ and 100 MHz values. Addition of sp42a/sp43a. • Table 20: Addition of 66 MHZ and 100 MHz values • Table 12: sp30 values. sp33b @100 MHz value. Removal of previous note 2. Modification of current note 2. • Figure 5, Figure 6, Figure 7, and Figure 8: Addition of notes • Section 6.2: Addition of note on PCI timing • Table 18, Table 32, Table 33, Table 36, Table 37: Addition of note 1 concerning minimum operating frequencies • Addition of statement before clock tables about selection of clock configuration and input frequency • Table 23 and Table 25: Addition of note 1 to CPM pins
0.2	11/2002	Table 25, “VR Pinout”: Addition of C18 to the Ground (GND) pin list (page 63)
0.1	—	Initial public release